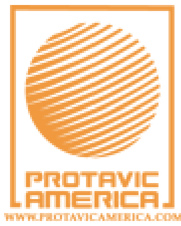


TS-0001

TECHNICAL SUPPORT FOR

ANE-54807M2
ANE-44037
ANE-44038

Ingot wafer slicing of Silicon, Sapphire, Quartz, or other material.

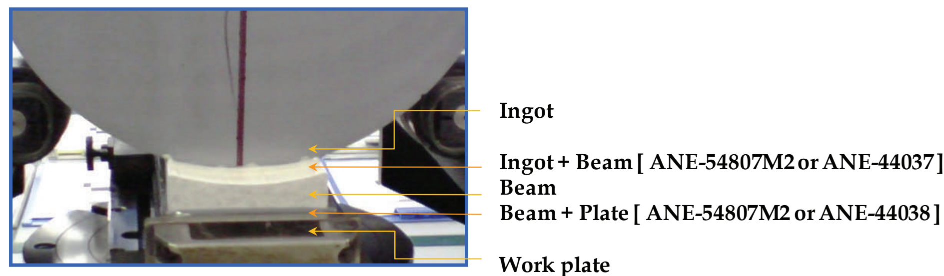
Features:
1. Fast cure time
2. Strong adhesion during slicing
3. Easy and fast epoxy removal
4. 1:1 Mix ratio

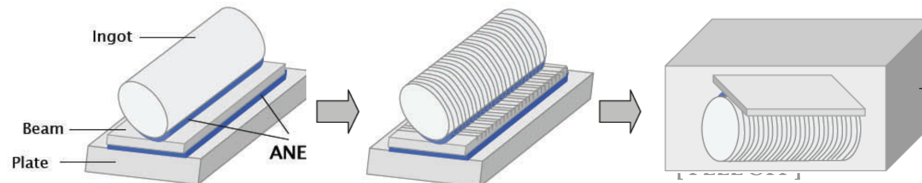
Benefits:
1. Set up time savings
2. Higher slicing yield
3. Increased production, less damage
4. Cartridge friendly, minimum training, easy to use

Increased production and higher yield will save production time and costs when using our adhesive, which will in turn save you money.

INGOT SLICING

The slicing process of the silicon ingot





	ANE-54807M2	ANE-44037	ANE-44038
Application	Beam to small ingot Beam to work plate	Beam to large ingot	Beam to work plate
Properties	Middle gel time High hardness Room Temp Cure High adhesive strength	Short gel time High hardness RT or heat cure High adhesive strength	Short gel time High hardness RT or heat cure Highest adhesive strength
Removal condition	Low temperature hot water (40 ~ 80℃)	Use high temperature hot water (60 ~ 90℃)	
Main application	Semiconductor (2-8 inch) Solar cell / LED	Semiconductor (8-12 inch) Silicon	Semiconductor Solar cell / LED

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